Product Change Notification - RMES-09VPXZ131

Date: 08 May 2017

Product Category: Ethernet PHYs

Notification subject: CCB 2922 Initial Notice: Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Notification text:

PCN Status:
Initial notification.

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of ASEK as an additional assembly site for selected products of the 0.18 wafer technology at DBHU available in 48L TQFP package using gold (Au) bond wire.

Pre Change:

Assembled at TICP using gold (Au) bond wire and CEL9200 molding compound material.

Post Change:

Assembled at ASEK using gold (Au) bond wire and G631H molding compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	TICP	ASEK
Lead frame material	C7025	C7025
Wire material	Au	Au
Die attach material	EN4900	CRM-1076WA
Mold compound material	CEL9200	G631H

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying ASEK as an additional assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

September 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been

issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	April 2017				->	September 2017				
Workweek	14	15	16	17		35	36	37	38	39
Initial PCN Issue Date				X						
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
April 28, 2017: Issued initial notification.
May 8, 2017: Re-issued the initial notification to notify all affected customers.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_RMES-09VPXZ131_Affected_CPN.pdf
PCN_RMES-09VPXZ131Qual_Plan.pdf
PCN_RMES-09VPXZ131_Affected_CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Number (CPN)

PCN_RMES-09VPXZ131
CATALOG_PART_NBR
KSZ8041FTL
KSZ8041FTLI
KSZ8041FTLI-TR
KSZ8041FTL-S
KSZ8041FTL-TR
KSZ8041TL
KSZ8041TLI
KSZ8041TLI-S
KSZ8041TLI-TR
KSZ8041TL-TR
SPNY801037
SPNY801037-TR
SPNY801049
SPNY801049-TR
SPNY801051
SPNY801051-TR
SPNY801066
SPNY801066-TR
SPNY801087
SPNY801087-TR
SPNZ801037
SPNZ801037-TR
SPNZ801049
SPNZ801049-TR
SPNZ801051
SPNZ801051-TR
SPNZ801053
SPNZ801053-TR
SPNZ801056
SPNZ801057
SPNZ801066
SPNZ801066-TR
SPNZ801087
SPNZ801087-TR